



June 4, 2019

NEWS RELEASE

Mitsui Kinzoku Completes Increase in Production Capacity of VSP[®]

Electro-Deposited Copper Foil for High-Frequency Circuit Boards

-VSP[®] production capacity of Taiwan Plant increased by 2.4 times to 420 tons per month-

Mitsui Mining & Smelting Co., Ltd. (President: Keiji Nishida; “Mitsui Kinzoku,” hereinafter) is pleased to announce that it has completed efforts to increase its production capacity of VSP[®] copper foil for high-frequency circuit boards, and has now commenced operation at increased capacity.

Mitsui Kinzoku’s VSP[®] copper foil for high-frequency circuit boards have been recognized highly by customers for their excellent surface smoothness and very low profile copper nodules on the surface that contribute greatly to reducing transmission loss in printed circuit boards at high frequency signal bands.

In April 2018, Mitsui Kinzoku expanded the monthly production capacity of its Taiwan plant (namely Taiwan Copper Foil Co., Ltd.) from 175 to 275 tons by partially upgrading the existing production line and installing new electro-deposition cells (as announced in a press release issued on July 20, 2017).

Since a further increase in demand was anticipated during the installation period, in addition to the installation of new electro-deposition equipment, Mitsui Kinzoku also made modifications to existing equipment for the production of conventional foil to give greater flexibility and enable their diversion to use in the production of VSP[®] foil. Efforts to increase VSP[®] production capacity to a maximum monthly capacity of 420 tons per month were completed at the end of May 2019.

With the startup of this increased production capacity, Mitsui Kinzoku is now sufficiently equipped to cater to the tremendous demand anticipated with the launch of 5G smartphone services, automated driving systems and connected cars in the Society5.0 and CASE (Connected, Autonomous, Shared & Services, Electric) era.

Mitsui Kinzoku is committed to offer stable quality and ensure adequate supply to its customers under the slogan “Material Intelligence”

[Inquiries]

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Conventional copper foil



VSP® foil

Photo: Copper foil surface reflecting an apple mango

*VSP® features excellent surface flatness smoothness like a mirror

(Reference)

Taiwan Copper Foil Co., Ltd.

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| (1) Name | Taiwan Copper Foil Co.,Ltd. |
| (2) Location | No. 150, Chenggong 3rd Road, Nantou City, Nantou County, 540,R.O.C |
| (3) President | Tatsuya Sudo |
| (4) Established | November 1980 |
| (5) Capital | NTD800M |
| (6) Investment | Mitsui Kinzoku (95%) |
| (7) Business Activities | Manufacturing of copper foil for printed circuit boards |